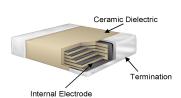
KEMET Surface Mount Ceramic

Revision I, 22 Sept 2010

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Characteristics and Typical Construction

- Standard EIA Chip Sizes
- COG, X7R, X5R, Y5V, Z5U, X8L & Ultra Stable X8R Dielectrics
- Termination code 'C' products support manufacture of RoHS-compliant EEE
- 4 3000 Volts
- Tape & Reel Packaging
- Bulk Cassette packaging available
- · Matte Tin finish terminations standard
- SnPb terminations available beginning August, 2005



RoHS Restricted Substance Content

Key for Determining Adherence to China RoHS and EU 2002/95/EC and 2005/618/EC Content Criteria¹

 $0 = \le MCV$, X = > MCV, X = > MCV, but EU RoHS Compliant with Exemption(s)

			Restricted Substance					Compliant Version				
		Substance and MCV ¹ Termination	Cd	Cr ⁶⁺	Pb	Hg	РВВ	PBDE	Size and Dielectric	Available since	Standard since	China RoHS Symbol ³
KEMET Product	Series	Code	< 0.01%	< 0.1%	< 0.1%	< 0.1%	< 0.1%	< 0.1%				0,
Ceramic Chip / Standard Ceramic Chip / High Voltage Tip & Ring/ KPS	CxxxxC								0402 C0G 0402 X7R	June-04	June-04	
Ceramic Open Mode Capacitors	CxxxxF				X C0G < 1.0nF ²							(e)
High Temperature (200°C) C0G	CxxxxH	- с	0	0	O COG ≥ 1.0nF,	0	0	O				
KEMET Commercial-Off-The-Shelf (COTS)	CxxxxT			•	X7R	_		"	> 0402 C0G	Jul-03	Jul-03	
Low Profile Ceramic Chip / Standard	CxxxxL				X5R, Y5V, Z5U							
Floating Electrode	CxxxxS											
Floating Electrode w/ Flexible Termination	CxxxxY								All Others	Aug-93	Aug-93	
Flexible Termination	CxxxxX											
Ceramic Chip / Standard Ceramic Chip / High Voltage Tip & Ring	CxxxxC											
Ceramic Open Mode Capacitors	CxxxxF	(not										60
High Temperature (200°C) C0G	CxxxxH	available for	0	0	x	0	0	o		lot Available		
KEMET Commercial-Off-The-Shelf (KCOTS)	CxxxxT	0201	U	U	^	U	0	0	1	IOL Available		
Low Profile Ceramic Chip / Standard	CxxxxL											
Floating Electrode	CxxxxS	products)										
Floating Electrode w/ Flexible Termination	CxxxxY											
Flexible Termination	CxxxxX											

¹MCV = Maximum Concentration Values per 2005/618/EC amending RoHS Directive 2002/95/EC and China RoHS criteria.

These components are in transition to a completely lead-free material set.

China RoHS Symbol based on current manufacturing. Refer to notes in Pb column for transition dates.

Soldering Capability Characteristics

	Matte Tin Termination	SnPb Termination		
Termination Material	Silver or Copper	Silver or Copper		
Termination Plating (Barrier)	100% Matte Tin (Nickel)	90Sn10 Pb (Nickel)		
Peak Temperature Capability	260°C	260°C		
Soldering Process Compatibility	Backward & Forward Compatible	Backward & Forward Compatible		
MSL Rating per J-STD-020C	Not Classified ⁴	Not Classified ⁴		
Tin Whisker Test Results	Class 2	Class 2		
based on JESD22-A121 and JESD201 ⁵	Class 2	Class 2		

⁴ MSL not classified for ceramic capacitors. J-STD-020 is applicable to non-hermetic surface mount devices, and is intended for plastic package components. KEMET ceramic chips are not encapsulated in a plastic package, so they are not susceptible to these effects. If an MSL were required, the rating this product would be considered MSL 1 or better.

Ordering

C 1206		С	104	K		G	A	C	
Ceramic	Case Size	Specification/	Capacitance	Capacitance Tolerance	W-14	Dielectric	Failure Rate/	End	
	(L"x W")	Series	Code (pF)		voitage	Dielectric	Design	Metallization^	
		C = Standard	2 Sig. Digits +			G = C0G	A = N/A	C = 100% Matte Sn	
		F = Open Mode	Number of			R = X7R	1 = KPS Single Chip Stack	L = SnPb (5% min)	
		H = High Temp (200°C)	Zeros.			P = X5R	2 = KPS Double Chip Stack		
		S = Floating Electrode	Use 9 for 1.0 - 9.9pF			H = Ultra Stable X8R	A = Group A Testing per MIL-PRF-55681		
		T = COTS	Use 8 for 0.599pF			N = X8L	PDA 8%		
		X = Flexible Termination	ex. 2.2pF = 229			U = Z 5U	B = Group A Testing per MIL-PRF-55681		
		Y = Floating Electrode w/	ex. 0.5pF = 508			V = Y5V	PDA 8%, DPA per EIA-469		
		Flexible Termination					C = Group A Testing per MIL-PRF-55681		
							PDA 8%, DPA per EIA-469,		
							Humidity per MIL-STD-202,		
							Method 103, Condition A		



Reel level KEMET EZ ID label indicates product content relative to substance restrictions of the EU RoHS Directive, 2002/95/EC, 2005/618/EC and China RoHS..

RoHS-PRC = Meets criteria without exemption

RoHS-PRC = Meets criteria without exemption RoHS-EU = Meets criteria with exemption RoHS-NO = Does not meet criteria





²All KEMET X7R and COG surface mount offerings already meet RoHS requirements. A limited group of these components contain a small portion of lead (Pb) that is exempt per Annex 1 to 2002/95/EC.

⁵ Per EIA/ECA component bulletin CB19, tin whiskering is not considered a reliability risk within the capacitor industry for non-Military / Hi-Rel applications.